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IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

Claims 1 - 7 (cancelled)

8. (previously presented) A method of interconnecting terminals comprising:

placing terminals so as to oppose each other with an anisotropic electrically conductive resin composition including at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles disposed between the opposing terminals;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured with the opposing terminals separated from each other by a space large enough to enable the particles to move laterally inside the space, wherein in the heating, the electrically conductive particles collect between the opposing terminals by melting and agglomeration of the electrically conductive particles, and the opposing terminals are electrically interconnected; and

curing the resin component.

9. (previously presented) A method of interconnecting

terminals as claimed in claim 8 wherein the resin component comprises a resin having reducing properties which can reduce at least one of the surface of the terminals and the surface of the electrically conductive particles.

10. (previously presented) A method of interconnecting terminals as claimed in claim 8 including completely filling the space between members on which the terminals are provided with the resin composition.

11. (previously presented) A method of mounting a semiconductor device comprising:

placing electrode pads of a semiconductor chip opposite circuit electrodes provided on a circuit substrate so as to correspond to the electrode pads with an anisotropic electrically conductive resin composition including at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles disposed between the opposing electrode pads and circuit electrodes;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completed cured with the opposing electrode pads and circuit electrodes separated from each other by a space large enough to enable the particles to move laterally inside the space, wherein in the heating, the electrically conductive particles collect between the opposing

electrode pads and circuit electrodes by melting and agglomeration of the electrically conductive particles, and the opposing electrode pads and circuit electrodes are electrically interconnected; and

curing the resin component.

12. (previously presented) A mounting method as claimed in claim 11 including completely filling the space between the semiconductor chip and the circuit substrate with the resin composition.

13. (previously presented) A mounting method as claimed in claim 12 wherein during the heating, substantially all of the electrically conductive particles in the resin composition collect in regions between opposing electrode pads and circuit electrodes.

14. (previously presented) A mounting method as claimed in claim 11 including performing the heating with the opposing electrode pads and circuit electrodes separated from each other by a distance which is at least a multiple of the diameter of the particles.

15. (previously presented) A method of interconnecting terminals as claimed in claim 8 including performing the heating with the terminals separated from each other by a distance which is at least a multiple of the diameter of the particles.

16. (new) A method of interconnecting terminals as claimed in claim 8 including metallurgically bonding a plurality of the particles to the terminals.

17. (new) A method of interconnecting terminals as claimed in claim 8 including arranging the plurality of terminals in a plurality of pairs, each pair comprising a first terminal and a second terminal opposing the first terminal, with the anisotropic electrically conductive resin composition disposed in a plurality of discrete masses each disposed between the first and second terminals of a different one of the pairs of terminals and spaced from the masses of the resin composition disposed between the other pairs of terminals, wherein the curing of the resin component is performed while leaving regions which do not contain the resin component or the electrically conductive particles between different pairs of the terminals.

18. (new) A method of interconnecting terminals as claimed in claim 8 wherein the electrically conductive particles have a melting point of at most 250°C.

19. (new) A method of interconnecting terminals as claimed in claim 8 wherein the electrically conductive particles comprise an Sn alloy.

20. (new) A method of interconnecting terminals

comprising:

placing a first member having a plurality of first terminals opposite a second member having a plurality of second terminals so that each of the first terminals opposes one of the second terminals to define a plurality of pairs of opposing terminals with an anisotropic electrically conductive resin composition including electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles completely filling a region between the first and second members which contains the pairs of opposing terminals;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured with the two terminals in each pair of opposing terminals separated from each other by a space large enough to enable the particles in the resin composition to move laterally inside the space, wherein in the heating, a plurality of the electrically conductive particles in the composition move from outside the spaces between the opposing terminals move into the spaces between the opposing terminals and accumulate in the spaces together with electrically conductive particles already inside the spaces prior to the heating by melting and agglomeration of the electrically conductive particles to electrically interconnect the two opposing terminals in each of the pairs of opposing terminals; and

curing the resin component.

21. (new) A method of interconnecting terminals as claimed  
20 including metallically bonding a plurality of the electrically  
conductive particles to the terminals.